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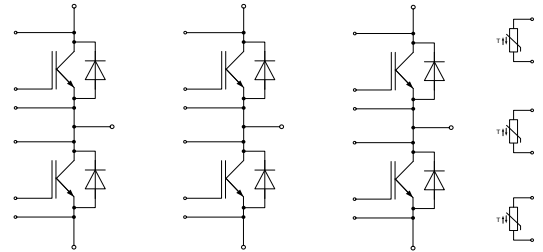
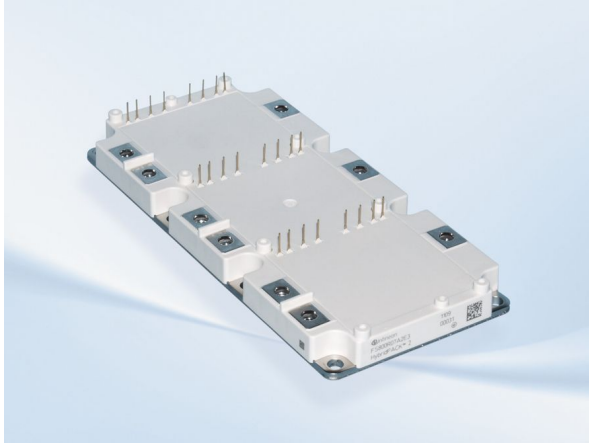
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HybridPACK™2 Modul mit Trench/Feldstopp IGBT3 und Emitter Controlled 3 Diode und NTC
HybridPACK™2 module with Trench/Fieldstop IGBT3 and Emitter Controlled 3 diode and NTC



$V_{CES} = 650V$
 $I_{C\ nom} = 600A / I_{CRM} = 1200A$

Typische Anwendungen

- Anwendungen im Automobil
- Hybrid-Elektrofahrzeuge (H)EV
- Hybrid-Nutzfahrzeuge
- Motorantriebe

Typical Applications

- Automotive Applications
- Hybrid Electrical Vehicles (H)EV
- Commercial Agriculture Vehicles
- Motor Drives

Elektrische Eigenschaften

- Erhöhte Sperrspannungsfestigkeit auf 650V
- Erweiterte Sperrschichttemperatur $T_{vj\ op}$
- Hohe Stromdichte
- Niederinduktives Design
- Niedrige Schaltverluste
- Niedriges V_{CEsat}
- $T_{vj\ op} = 150^{\circ}C$
- $T_{vj\ op} = 175^{\circ}C$
- Trench IGBT 3
- V_{CEsat} mit positivem Temperaturkoeffizienten

Electrical Features

- Increased blocking voltage capability to 650V
- Extended Operation Temperature $T_{vj\ op}$
- High Current Density
- Low Inductive Design
- Low Switching Losses
- Low V_{CEsat}
- $T_{vj\ op} = 150^{\circ}C$
- $T_{vj\ op} = 175^{\circ}C$
- Trench IGBT 3
- V_{CEsat} with positive Temperature Coefficient

Mechanische Eigenschaften

- 2,5 kV AC 1min Isolationsfestigkeit
- Direkt gekühlte Bodenplatte
- Hohe Leistungsdichte
- Integrierter NTC Temperatur Sensor
- Isolierte Bodenplatte

Mechanical Features

- 2.5 kV AC 1min Insulation
- Direct Cooled Base Plate
- High Power Density
- Integrated NTC temperature sensor
- Isolated Base Plate

Module Label Code

Barcode Code 128



DMX - Code



Content of the Code

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

prepared by: WJ	date of publication: 2014-05-28	
approved by: MM	revision: 3.0	



IGBT, Wechselrichter / IGBT, Inverter

Höchstzulässige Werte / Maximum Rated Values

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	650	V
Implementierter Kollektor-Strom Implemented collector current		I_{CN}	600	A
Kollektor-Dauergleichstrom Continuous DC collector current	$T_F = 75^{\circ}\text{C}, T_{vj\ max} = 175^{\circ}\text{C}$ $T_F = 25^{\circ}\text{C}, T_{vj\ max} = 175^{\circ}\text{C}$	$I_{C\ nom}$ I_C	400 530	A A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\ \text{ms}$	I_{CRM}	1200	A
Gesamt-Verlustleistung Total power dissipation	$T_F = 25^{\circ}\text{C}, T_{vj\ max} = 175^{\circ}\text{C}$	P_{tot}	1300	W
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		V_{GES}	+/-20	V

Charakteristische Werte / Characteristic Values

			min.	typ.	max.		
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 400\ \text{A}, V_{GE} = 15\ \text{V}$ $I_C = 400\ \text{A}, V_{GE} = 15\ \text{V}$ $I_C = 400\ \text{A}, V_{GE} = 15\ \text{V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\ sat}$	1,30 1,35 1,40	1,50	V V V	
Gate-Schwellenspannung Gate threshold voltage	$I_C = 9,60\ \text{mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		V_{Geth}	4,9	5,8	6,5	V
Gateladung Gate charge	$V_{GE} = -15\ \text{V} \dots +15\ \text{V}$		Q_G	6,50			μC
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		R_{Gint}	0,5			Ω
Eingangskapazität Input capacitance	$f = 1\ \text{MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\ \text{V}, V_{GE} = 0\ \text{V}$		C_{ies}	39,0			nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 1\ \text{MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\ \text{V}, V_{GE} = 0\ \text{V}$		C_{res}	1,15			nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 650\ \text{V}, V_{GE} = 0\ \text{V}, T_{vj} = 25^{\circ}\text{C}$		I_{CES}			5,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\ \text{V}, V_{GE} = 20\ \text{V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}			400	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 400\ \text{A}, V_{CE} = 300\ \text{V}$ $V_{GE} = \pm 15\ \text{V}$ $R_{Gon} = 2,2\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_{don}	0,09 0,10 0,10			μs μs μs
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 400\ \text{A}, V_{CE} = 300\ \text{V}$ $V_{GE} = \pm 15\ \text{V}$ $R_{Gon} = 2,2\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_r	0,08 0,09 0,09			μs μs μs
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 400\ \text{A}, V_{CE} = 300\ \text{V}$ $V_{GE} = \pm 15\ \text{V}$ $R_{Goff} = 1,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_{doff}	0,44 0,47 0,48			μs μs μs
Fallzeit, induktive Last Fall time, inductive load	$I_C = 400\ \text{A}, V_{CE} = 300\ \text{V}$ $V_{GE} = \pm 15\ \text{V}$ $R_{Goff} = 1,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_f	0,03 0,05 0,06			μs μs μs
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 400\ \text{A}, V_{CE} = 300\ \text{V}, L_S = 20\ \text{nH}$ $V_{GE} = \pm 15\ \text{V}, di/dt = 4600\ \text{A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Gon} = 2,2\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{on}	9,00 11,0 11,5			mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 400\ \text{A}, V_{CE} = 300\ \text{V}, L_S = 20\ \text{nH}$ $V_{GE} = \pm 15\ \text{V}, du/dt = 2900\ \text{V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Goff} = 1,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{off}	14,0 17,5 18,5			mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\ \text{V}, V_{CC} = 360\ \text{V}$ $V_{CEmax} = V_{CES} - L_{SCE} \cdot di/dt$	$t_P \leq 8\ \mu\text{s}, T_{vj} = 25^{\circ}\text{C}$ $t_P \leq 6\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$	I_{SC}	4200 3000			A A
Wärmewiderstand, Chip bis Kühl-Flüssigkeit Thermal resistance, junction to cooling fluid	pro IGBT / per IGBT cooling fluid = 50% water/50% ethylenglycol; $\Delta V/\Delta t = 10,0\ \text{dm}^3/\text{min}$		R_{thJF}			0,116	K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\ op}$	-40		150	$^{\circ}\text{C}$

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Diode, Wechselrichter / Diode, Inverter

Höchstzulässige Werte / Maximum Rated Values

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	650	V
Dauergleichstrom Continuous DC forward current		I_F	400	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	I_{FRM}	1200	A
Grenzlastintegral I^2t - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	12000 11500	A^2s A^2s

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 400\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 400\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 400\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_F	1,40 1,35 1,30	1,75	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 400\text{ A}, -di_F/dt = 4600\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	I_{RM}	190 290 320		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 400\text{ A}, -di_F/dt = 4600\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	Q_r	14,0 31,0 36,0		μC μC μC
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 400\text{ A}, -di_F/dt = 4600\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{rec}	3,50 7,00 8,50		mJ mJ mJ
Wärmewiderstand, Chip bis Kühl-Flüssigkeit Thermal resistance, junction to cooling fluid	pro Diode / per diode cooling fluid = 50% water/50% ethylenglycol; $\Delta V/\Delta t = 10,0\text{ dm}^3/\text{min}$		R_{thJF}		0,165	K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

NTC-Widerstand / NTC-Thermistor

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Nennwiderstand Rated resistance	$T_C = 25^{\circ}\text{C}$	R_{25}		5,00		$\text{k}\Omega$
Abweichung von R100 Deviation of R100	$T_C = 100^{\circ}\text{C}, R_{100} = 493\ \Omega$	$\Delta R/R$	-5		5	%
Verlustleistung Power dissipation	$T_C = 25^{\circ}\text{C}$	P_{25}			20,0	mW
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/50}$		3375		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/80}$		3411		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/100}$		3433		K

Angaben gemäß gültiger Application Note.
Specification according to the valid application note.

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Modul / Module

Isolations-Prüfspannung Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V _{ISOL}	2,5			kV
Material Modulgrundplatte Material of module baseplate			Cu			
Innere Isolation Internal isolation	Basisisolierung (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140)		Al ₂ O ₃			
Kriechstrecke Creepage distance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		7,0 5,5			mm
Luftstrecke Clearance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		7,0 5,0			mm
Vergleichszahl der Kriechwegbildung Comperative tracking index		CTI	> 200			
			min.	typ.	max.	
Druckabfall im Kühlkreislauf* Pressure drop in cooling circuit*	$\Delta V/\Delta t = 10,0 \text{ dm}^3/\text{min}$; T _F = 25°C cooling fluid = 50% water/50% ethylenglycol	Δp		119		mbar
Höchstzulässiger Druck im Kühlkreislauf Maximum pressure in cooling circuit		p			2,5	bar
Modulstreuintuktivität Stray inductance module		L _{SCE}		14		nH
Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip	T _F = 25°C, pro Schalter / per switch	R _{CC+EE'}		0,80		mΩ
Lagertemperatur Storage temperature		T _{stg}	-40		125	°C
Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting	Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note	M	3,00	-	6,00	Nm
Anzugsdrehmoment f. elektr. Anschlüsse Terminal connection torque	Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note	M	2,5	-	5,0	Nm
Gewicht Weight		G		1340		g

* Kühleraufbau gemäß gültiger Application Note.
* Cooler setup according to the valid application note.

Kundenspezifisch / Customized

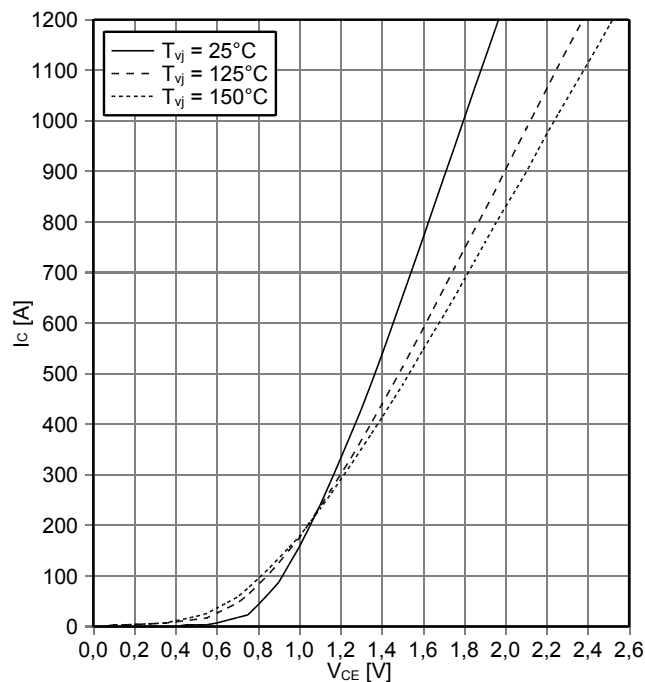
Collector-emitter voltage (tested end of line)	T _{vj} = 25°C	V _{ces}	680			V
Temperature under switching conditions	Max. 30h over life time inverter / brake-chopper 10s within period of 10min	for T _{vj op}			175	°C
Short circuit ruggedness specified at 150°C	s. IGBT characteristic values					

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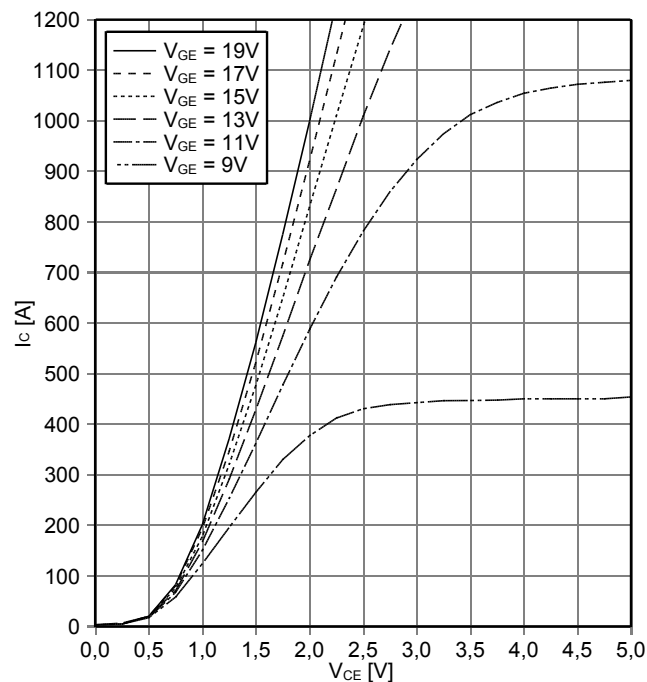
Ausgangskennlinie IGBT, Wechselrichter (typisch)
output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



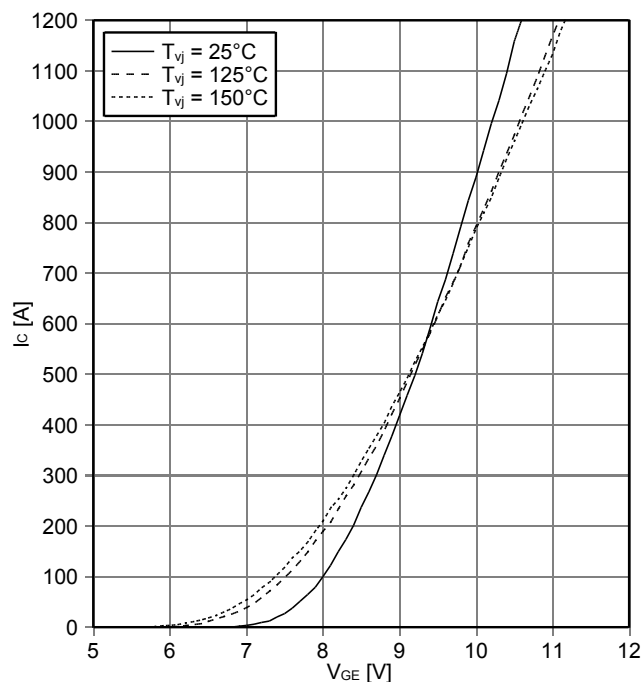
Ausgangskennlinienfeld IGBT, Wechselrichter (typisch)
output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



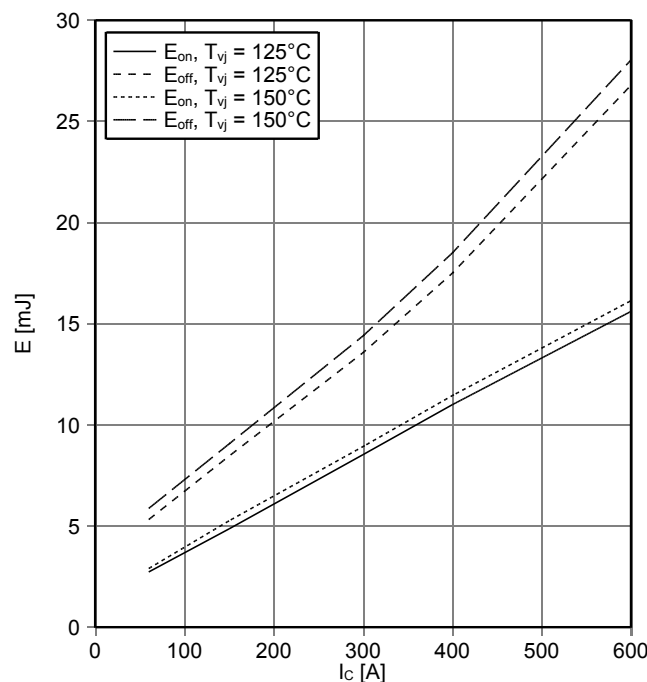
Übertragungscharakteristik IGBT, Wechselrichter (typisch)
transfer characteristic IGBT, Inverter (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



Schaltverluste IGBT, Wechselrichter (typisch)
switching losses IGBT, Inverter (typical)

$E_{on} = f(I_C)$, $E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 2.2\ \Omega$, $R_{Goff} = 1\ \Omega$, $V_{CE} = 300\text{ V}$

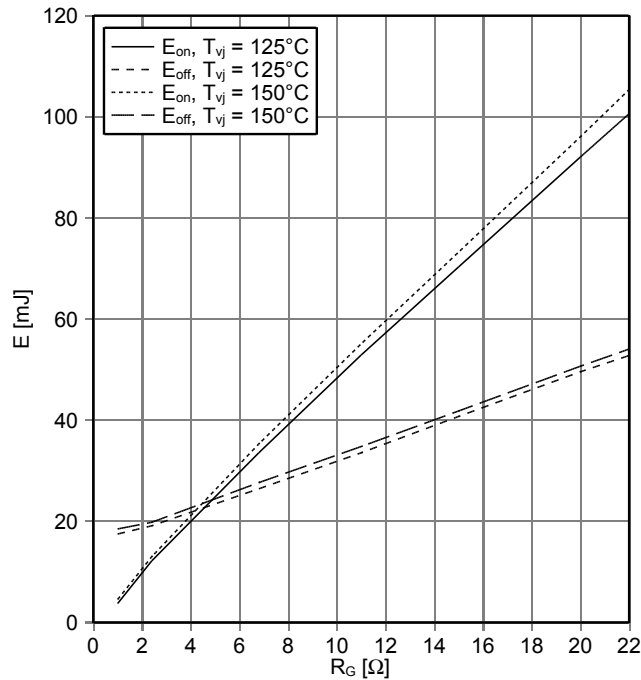


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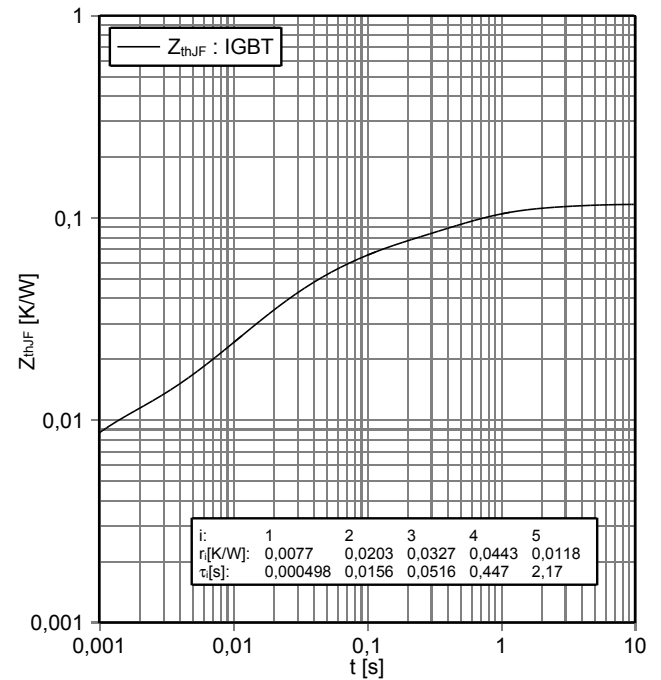
Schaltverluste IGBT, Wechselrichter (typisch)
switching losses IGBT, Inverter (typical)

$E_{on} = f(R_G), E_{off} = f(R_G)$
 $V_{GE} = \pm 15\text{ V}, I_C = 400\text{ A}, V_{CE} = 300\text{ V}$



Transienter Wärmewiderstand IGBT, Wechselrichter
transient thermal impedance IGBT, Inverter

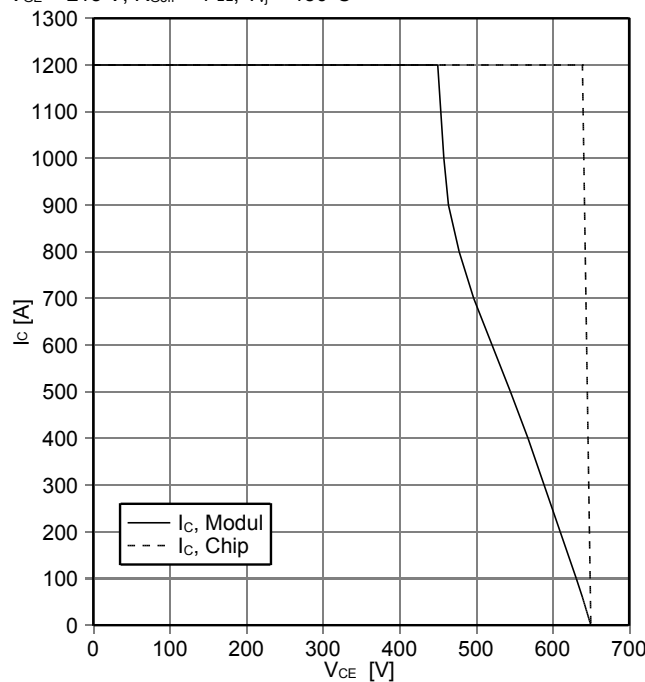
$Z_{thJF} = f(t)$ ($\Delta V/\Delta t = 10\text{ dm}^3/\text{min}$)



Sicherer Rückwärts-Arbeitsbereich IGBT, Wechselrichter
(RBSOA)

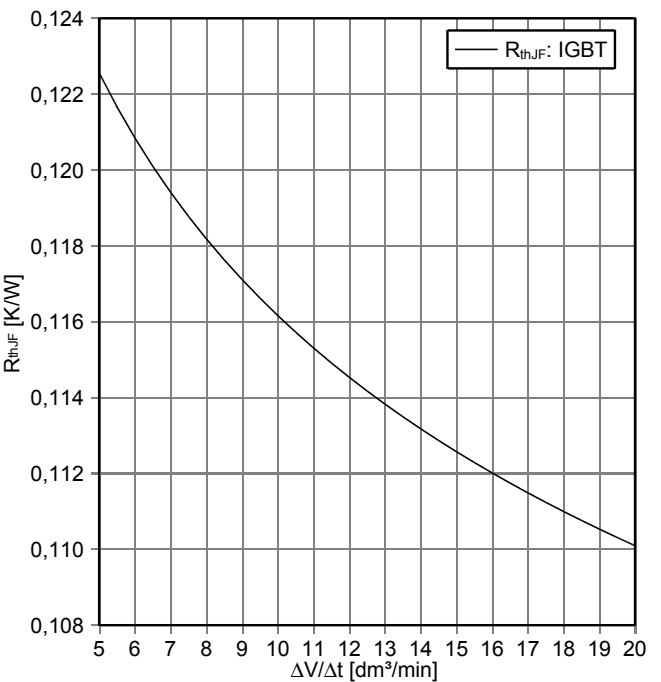
reverse bias safe operating area IGBT, Inverter (RBSOA)

$I_C = f(V_{CE})$
 $V_{GE} = \pm 15\text{ V}, R_{Goff} = 1\ \Omega, T_{vj} = 150^\circ\text{C}$



Wärmewiderstand IGBT, Wechselrichter
thermal impedance IGBT, Inverter

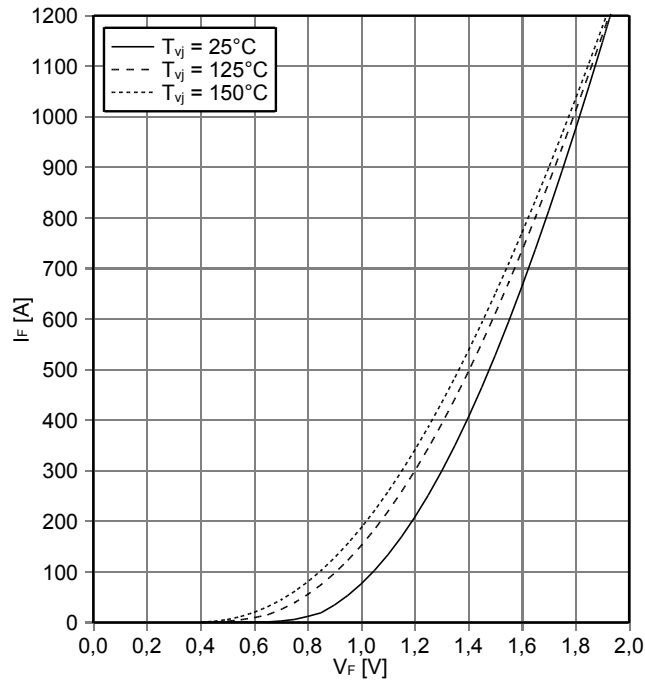
$R_{thJF} = f(\Delta V/\Delta t)$
cooling fluid = 50% water/50% ethylenglycol



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Durchlasskennlinie der Diode, Wechselrichter (typisch)
forward characteristic of Diode, Inverter (typical)

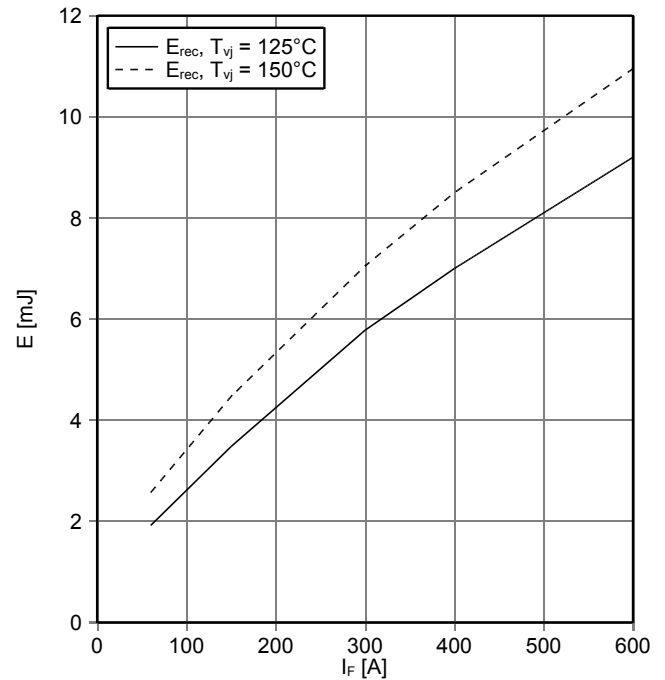
$I_F = f(V_F)$



Schaltverluste Diode, Wechselrichter (typisch)
switching losses Diode, Inverter (typical)

$E_{rec} = f(I_F)$

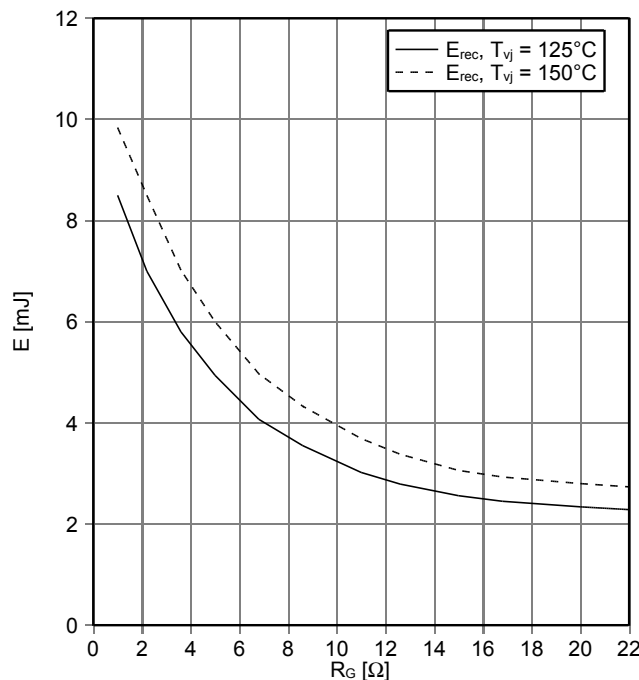
$R_{Gon} = 2.2 \Omega, V_{CE} = 300 V$



Schaltverluste Diode, Wechselrichter (typisch)
switching losses Diode, Inverter (typical)

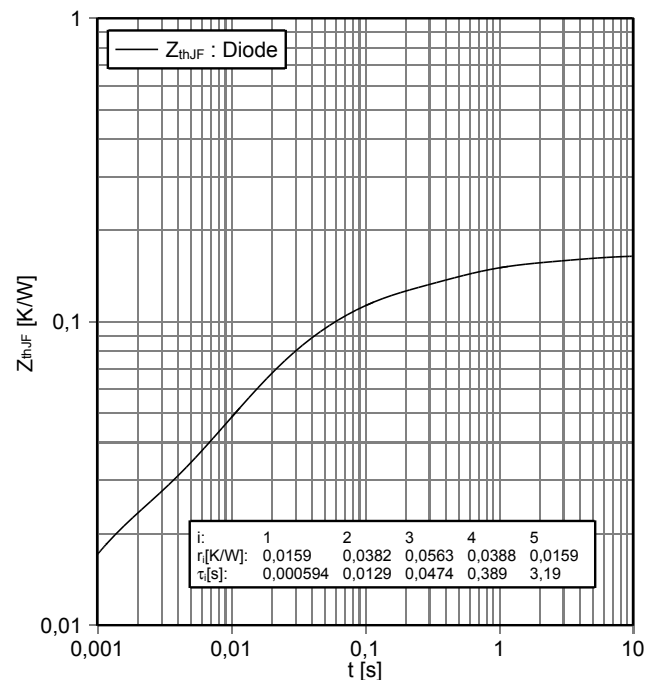
$E_{rec} = f(R_G)$

$I_F = 400 A, V_{CE} = 300 V$



Transienter Wärmewiderstand Diode, Wechselrichter
transient thermal impedance Diode, Inverter

$Z_{thJF} = f(t) \quad (\Delta V/\Delta t = 10 \text{ dm}^3/\text{min})$



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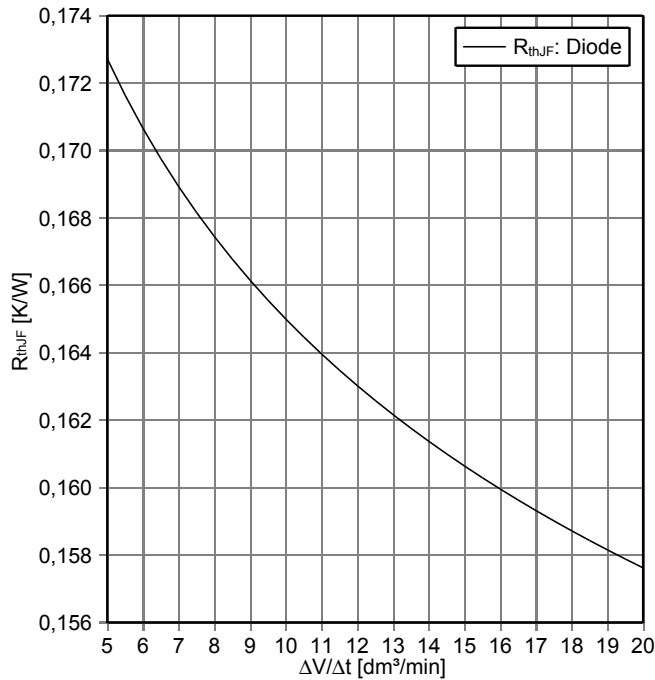


Wärmewiderstand Diode, Wechselrichter

thermal impedance Diode, Inverter

$R_{th,IF} = f(\Delta V/\Delta t)$

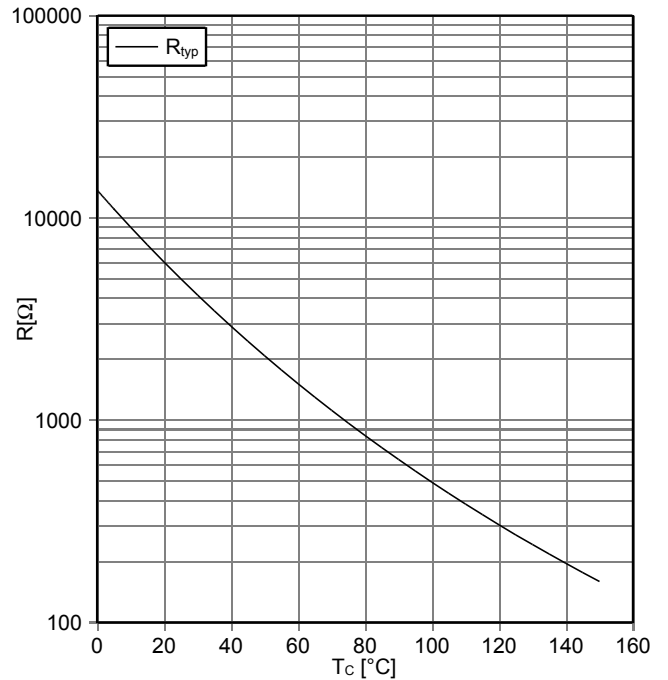
cooling fluid = 50% water/50% ethylenglycol



NTC-Widerstand-Temperaturkennlinie (typisch)

NTC-Thermistor-temperature characteristic (typical)

$R = f(T)$

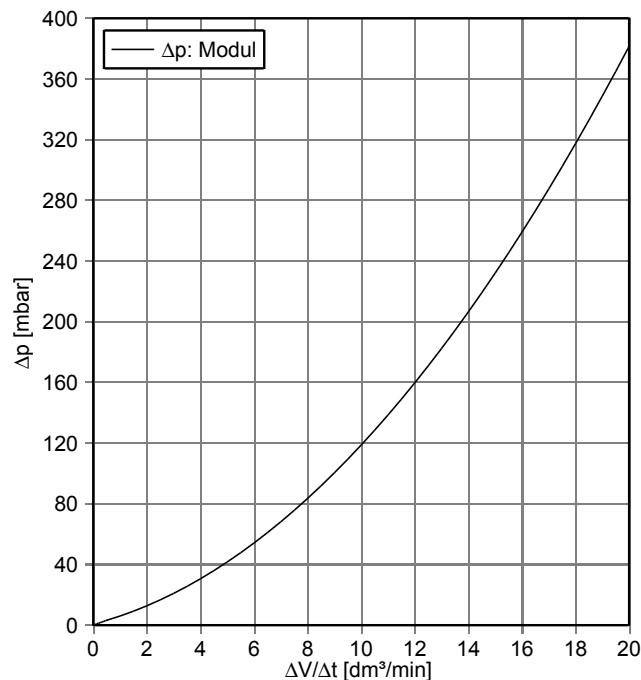


Druckabfall im Kühlkreislauf*

pressure drop in cooling circuit*

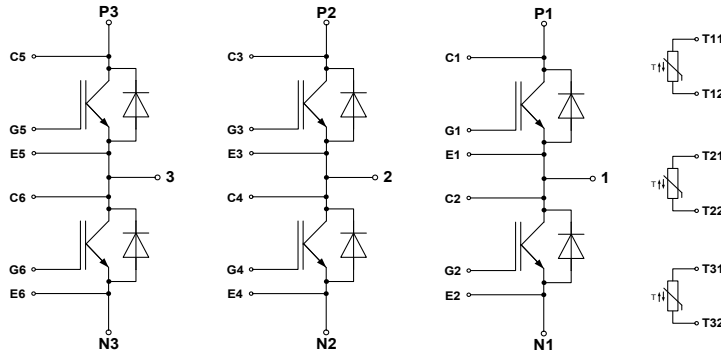
$\Delta p = f(\Delta V/\Delta t)$

cooling fluid = 50% water/50% ethylenglycol, T_F = 25°C



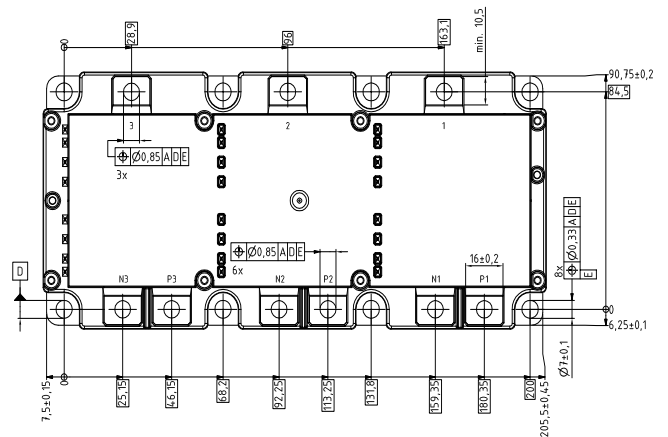
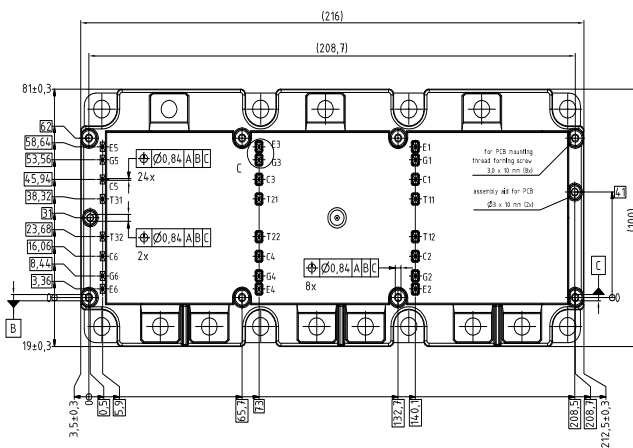
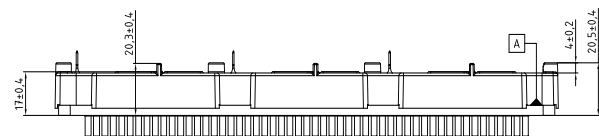
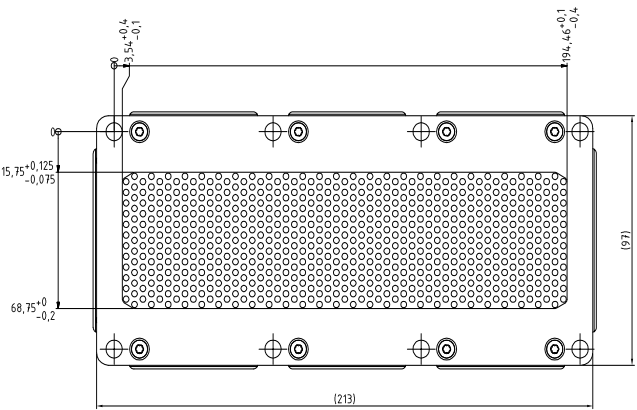
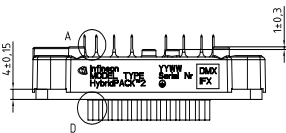
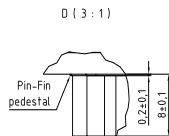
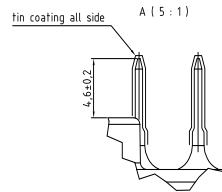
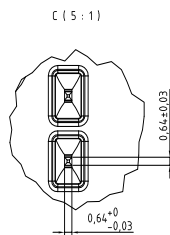
prepared by: WJ	date of publication: 2014-05-28
approved by: MM	revision: 3.0

Schaltplan / circuit_diagram_headline



Gehäuseabmessungen / package outlines

ISO 8015 principle of independency dimensions ISO 14405 \square target geometry according CAD file with general tolerances \square method of least-squares	Drawing: D00018099.00.E	edges	general tolerances	surface
	DIN ISO 13715	1. DIN 16742-TG6 2. DIN ISO 2768-mk	DIN EN ISO 1302	



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